

FEATURES

- Complete Dual DC/DC Regulator System
- Input Voltage Range: 2.375V to 5.5V
- Dual 8A Outputs, or Single 16A Output with a 0.6V to 5V Range
- Output Voltage Tracking and Margining
- $\pm 1.75\%$ Total DC Output Error (-40°C to 125°C)
- Current Mode Control/Fast Transient Response
- Power Good Tracking and Margining
- Overcurrent/Thermal Shutdown Protection
- Onboard Frequency Synchronization
- Spread Spectrum Frequency Modulation
- Multiphase Operation
- Selectable Burst Mode[®] Operation
- Output Overvoltage Protection
- Gold-Pad Finish Allows Soldering with Pb and Pb-Free Solder Paste
- Small Surface Mount Footprint, Low Profile (15mm \times 15mm \times 2.82mm) LGA Package

APPLICATIONS

- Telecom, Networking and Industrial Equipment
- Storage and ATCA, PCI Express Cards
- Battery Operated Equipment

 , LT, LTC, LTM and Burst Mode are registered trademarks of Linear Technology Corporation. μ Module is a trademark of Linear Technology Corporation. All other trademarks are the property of their respective owners. Protected by U.S. Patents, including 5481178, 6580258, 6304066, 6127815, 6498466, 6611131, 6724174.

DESCRIPTION

The LTM[®]4616 is a complete dual 2-phase 8A per channel switch mode DC/DC power regulator system in a 15mm \times 15mm surface mount LGA package. Included in the package are the switching controller, power FETs, inductor and all support components. Operating from an input voltage range of 2.375V to 5.5V, the LTM4616 supports two outputs within a voltage range of 0.6V to 5V, each set by a single external resistor. This high efficiency design delivers up to 8A continuous current (10A peak) for each output. Only bulk input and output capacitors are needed, depending on ripple requirement. The part can also be configured for a two phase single output at up to 16A.

The low profile package (2.82mm) enables utilization of unused space on the back side of PC boards for high density point-of-load regulation.

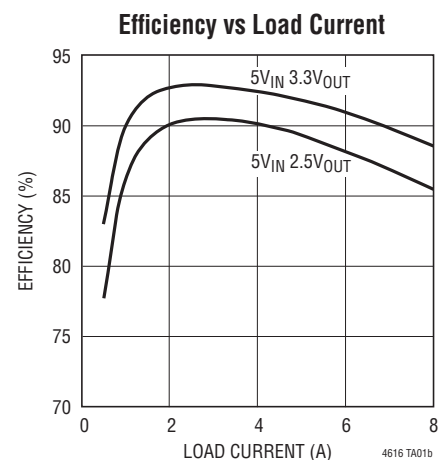
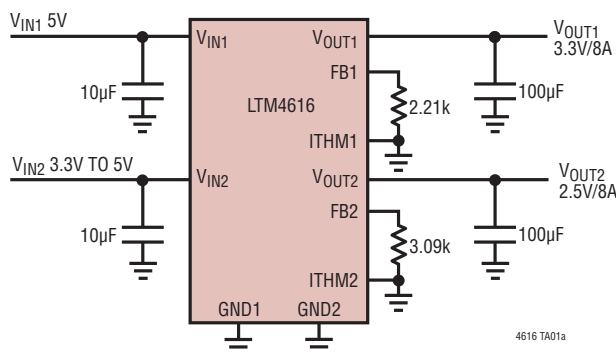
Fault protection features include overvoltage protection, overcurrent protection and thermal shutdown. The power module is offered in a space saving and thermally enhanced 15mm \times 15mm \times 2.82mm LGA package. The LTM4616 is Pb-free and RoHS compliant.

Different Combinations of Input and Output

Number of Inputs	Number of Outputs	I_{OUT} (MAX)
2	2	8A, 8A
2	1	16A
1	2	8A, 8A
1	1	16A

TYPICAL APPLICATION

Dual Output DC/DC μ Module[™] Regulator



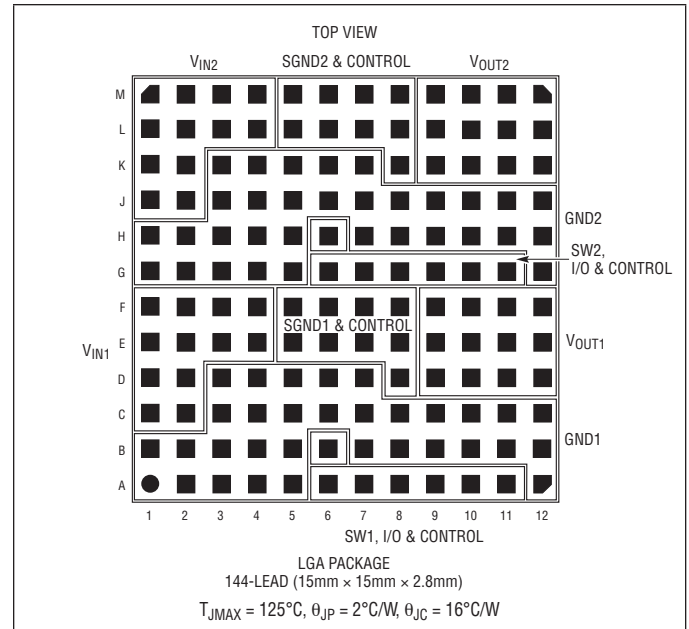
LTM4616

ABSOLUTE MAXIMUM RATINGS

(Note 1)

V_{IN1} , SV_{IN1} , V_{IN2} , SV_{IN2}	-0.3V to 6V
CLKOUT1, CLKOUT2.....	-0.3V to 2V
PGOOD1, PLLLPF1, CLKIN1, PHMODE1, MODE1, PGOOD2, PLLLPF2, CLKIN2, PHMODE2, MODE2.....	-0.3V to V_{IN}
I_{TH1} , I_{THM1} , RUN1, FB1, TRACK1, MGN1, BSEL1, I_{TH2} , I_{THM2} , RUN2, FB2, TRACK2, MGN2, BSEL2.....	-0.3V to V_{IN}
V_{OUT1} , V_{OUT2} , SW1, SW2.....	-0.3V to V_{IN}
Internal Operating Temperature Range (Note 2)	-40°C to 125°C
Junction Temperature	125°C
Storage Temperature Range.....	-55°C to 125°C

PIN CONFIGURATION



ORDER INFORMATION

LEAD FREE FINISH	TRAY	PART MARKING*	PACKAGE DESCRIPTION	INTERNAL TEMPERATURE RANGE
LTM4616EV#PBF	LTM4616EV#PBF	LTM4616V	144-Lead (15mm × 15mm × 2.82mm) LGA	-40°C to 125°C
LTM4616IV#PBF	LTM4616IV#PBF	LTM4616V	144-Lead (15mm × 15mm × 2.82mm) LGA	-40°C to 125°C

Consult LTC Marketing for parts specified with wider operating temperature ranges. *The temperature grade is identified by a label on the shipping container.

For more information on lead free part marking, go to: <http://www.linear.com/leadfree/>

This product is only offered in trays. For more information go to: <http://www.linear.com/packaging/>

ELECTRICAL CHARACTERISTICS The ● denotes the specifications which apply over the -40°C to 125°C internal operating temperature range. $T_A = 25^{\circ}\text{C}$, $V_{IN} = 5\text{V}$ unless otherwise noted. Per the typical application in Figure 18. Specified as each channel (Note 3).

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
$V_{IN1(DC)}$, $V_{IN2(DC)}$	Input DC Voltage		● 2.375		5.5	V	
$V_{OUT1(DC)}$, $V_{OUT2(DC)}$	Output Voltage, Total Variation with Line and Load	$C_{IN} = 10\mu\text{F} \times 1$, $C_{OUT} = 100\mu\text{F}$ Ceramic, 100μF POSCAP, $R_{FB} = 6.65\text{k}$ $V_{IN} = 2.375\text{V}$ to 5.5V, $I_{OUT} = I_{OUT(DC)MIN}$ to $I_{OUT(DC)MAX}$ (Note 4)		1.472	1.49	1.508	V
			● 1.464	1.49	1.516	V	
Input Specifications							
$V_{IN1(UVLO)}$, $V_{IN2(UVLO)}$	Undervoltage Lockout Threshold	SV_{IN} Rising SV_{IN} Falling	2.05	2.2	2.35	V	
			1.85	2.0	2.15	V	

ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the -40°C to 125°C internal operating temperature range. $T_A = 25^{\circ}\text{C}$, $V_{\text{IN}} = 5\text{V}$ unless otherwise noted. Per the typical application in Figure 18. Specified as each channel (Note 3).

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$I_{\text{Q}}(\text{VIN1}, \text{VIN2})$	Input Supply Bias Current	$V_{\text{IN}} = 3.3\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, No Switching, Mode = V_{IN}		400		μA
		$V_{\text{IN}} = 3.3\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, No Switching, Mode = 0V		1.15		mA
		$V_{\text{IN}} = 3.3\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, Switching Continuous		55		mA
		$V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, No Switching, Mode = V_{IN}		450		μA
$I_{\text{S}}(\text{VIN1}, \text{VIN2})$	Input Supply Current	$V_{\text{IN}} = 2.375\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, $I_{\text{OUT}} = 5\text{A}$		3.75		A
		$V_{\text{IN}} = 3.3\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, $I_{\text{OUT}} = 8\text{A}$		4.5		A
		$V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, $I_{\text{OUT}} = 8\text{A}$		2.93		A
		Shutdown, $\text{RUN} = 0$, $V_{\text{IN}} = 5\text{V}$		1		μA

Output Specifications

$I_{\text{OUT1}}(\text{DC}), I_{\text{OUT2}}(\text{DC})$	Output Continuous Current Range (Note 4)	$V_{\text{OUT}} = 1.5\text{V}$ $V_{\text{IN}} = 3.3\text{V}, 5.5\text{V}$ $V_{\text{IN}} = 2.375\text{V}$		0 0	8 5	A A	
$\frac{\Delta V_{\text{OUT1}}(\text{LINE})}{V_{\text{OUT1}}}, \frac{\Delta V_{\text{OUT2}}(\text{LINE})}{V_{\text{OUT2}}}$	Line Regulation Accuracy	$V_{\text{OUT}} = 1.5\text{V}$, V_{IN} from 2.375V to 5.5V, $I_{\text{OUT}} = 0\text{A}$	●	0.1	0.25	%/V	
$\frac{\Delta V_{\text{OUT1}}(\text{LOAD})}{V_{\text{OUT1}}}, \frac{\Delta V_{\text{OUT2}}(\text{LOAD})}{V_{\text{OUT2}}}$	Load Regulation Accuracy	$V_{\text{OUT}} = 1.5\text{V}$ (Note 4) $V_{\text{IN}} = 3.3\text{V}, 5.5\text{V}$, $I_{\text{LOAD}} = 0\text{A}$ to 8A $V_{\text{IN}} = 2.375\text{V}$, $I_{\text{LOAD}} = 0\text{A}$ to 5A	● ●	0.3 0.3	0.5 0.5	% %	
$V_{\text{OUT1}}(\text{AC}), V_{\text{OUT2}}(\text{AC})$	Output Ripple Voltage	$I_{\text{OUT}} = 0\text{A}$, $C_{\text{OUT}} = 100\mu\text{F}$ X5R Ceramic, $V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$		10		$\text{mV}_{\text{P-P}}$	
$f_{\text{S1}}, f_{\text{S2}}$	Switching Frequency	$I_{\text{OUT}} = 8\text{A}$, $V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$		1.25	1.5	1.75	MHz
$f_{\text{SYNC1}}, f_{\text{SYNC2}}$	SYNC Capture Range			0.75	2.25	MHz	
$\frac{\Delta V_{\text{OUT1}}(\text{START})}{V_{\text{OUT1}}}, \frac{\Delta V_{\text{OUT2}}(\text{START})}{V_{\text{OUT2}}}$	Turn-On Overshoot	$C_{\text{OUT}} = 100\mu\text{F}$, $V_{\text{OUT}} = 1.5\text{V}$, $I_{\text{OUT}} = 0\text{A}$ $V_{\text{IN}} = 3.3\text{V}$ $V_{\text{IN}} = 5\text{V}$		10 10		mV mV	
$t_{\text{START1}}, t_{\text{START2}}$	Turn-On Time	$C_{\text{OUT}} = 100\mu\text{F}$, $V_{\text{OUT}} = 1.5\text{V}$, $I_{\text{OUT}} = 1\text{A}$, Resistive Load, Track = V_{IN} , $V_{\text{IN}} = 5\text{V}$		100		μs	
$\frac{\Delta V_{\text{OUT1}}(\text{LS})}{V_{\text{OUT1}}}, \frac{\Delta V_{\text{OUT2}}(\text{LS})}{V_{\text{OUT2}}}$	Peak Deviation for Dynamic Load	Load: 0% to 50% to 0% of Full Load, $C_{\text{OUT}} = 100\mu\text{F}$ Ceramic x2, 470 μF POSCAP, $V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$		20		mV	
$t_{\text{SETTLE1}}, t_{\text{SETTLE2}}$	Settling Time for Dynamic Load Step	Load: 0% to 50% to 0% of Full Load, $V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$, $C_{\text{OUT}} = 100\mu\text{F}$		10		μs	
$I_{\text{OUT1}}(\text{PK}), I_{\text{OUT2}}(\text{PK})$	Output Current Limit	$C_{\text{OUT}} = 100\mu\text{F}$ $V_{\text{IN}} = 2.375\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$ $V_{\text{IN}} = 3.3\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$ $V_{\text{IN}} = 5\text{V}$, $V_{\text{OUT}} = 1.5\text{V}$		8 11 13		A A A	

Control Section

FB1, FB2	Voltage at FB Pin	$I_{\text{OUT}} = 0\text{A}$, $V_{\text{OUT}} = 1.5\text{V}$, $V_{\text{IN}} = 2.375\text{V}$ to 5.5V	●	0.590 0.587	0.596 0.596	0.602 0.606	V V
SS Delay	Internal Soft-Start Delay			90		μs	
I_{FB}				0.2		μA	
$V_{\text{RUN1}}, V_{\text{RUN2}}$	RUN Pin On/Off Threshold	RUN Rising RUN Falling		1.4 1.3	1.55 1.4	1.7 1.5	V V
TRACK1, TRACK2	Tracking Threshold (Rising) Tracking Threshold (Falling) Tracking Disable Threshold	RUN = V_{IN} RUN = 0V			0.57 0.18 $V_{\text{IN}} - 0.5$	V V V	

ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the -40°C to 125°C internal operating temperature range. $T_A = 25^{\circ}\text{C}$, $V_{IN} = 5\text{V}$ unless otherwise noted. Per the typical application in Figure 18. Specified as each channel (Note 3).

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R_{FBH1}, R_{FBH2}	Resistor Between V_{OUT} and FB Pins		9.95	10	10.05	$k\Omega$
$\Delta V_{PGOOD1}, \Delta V_{PGOOD2}$	PGOOD Range			± 10		%
%Margining	Output Voltage Margining Percentage	$MGN = V_{IN}, BSEL = 0V$ $MGN = V_{IN}, BSEL = V_{IN}$ $MGN = V_{IN}, BSEL = \text{Float}$ $MGN = 0V, BSEL = 0V$ $MGN = 0V, BSEL = V_{IN}$ $MGN = 0V, BSEL = \text{Float}$	4 9 14 -4 -9 -14	5 10 15 -5 -10 -15	6 11 16 -6 -11 -16	% % % % % %

Note 1: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

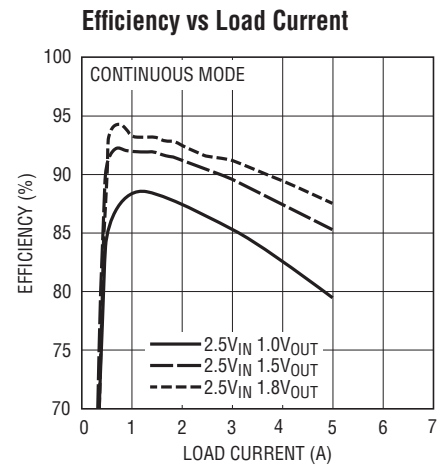
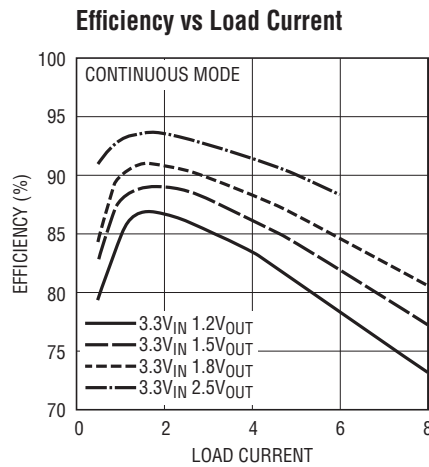
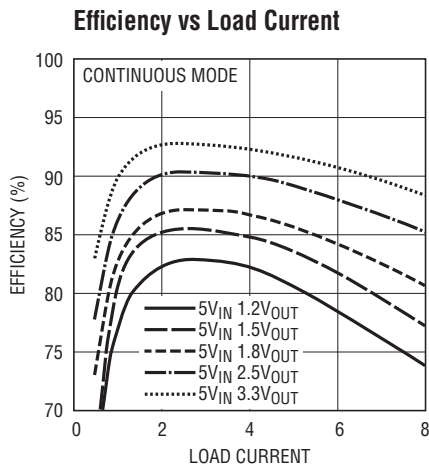
Note 2: The LTM4616E is guaranteed to meet performance specifications over the 0°C to 125°C internal operating temperature range. Specifications over the full -40°C to 125°C internal operating temperature range are assured by design, characterization and correlation with statistical process

controls. The LTM4616I is guaranteed to meet specifications over the full internal operating temperature range. Note that the maximum ambient temperature is determined by specific operating conditions in conjunction with board layout, the rated package thermal resistance and other environmental factors.

Note 3: Two channels are tested separately and the same testing conditions are applied to each channel.

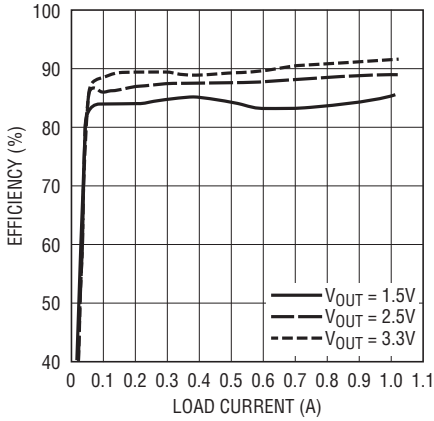
Note 4: See Output Current Derating curves for different V_{IN} , V_{OUT} and T_A .

TYPICAL PERFORMANCE CHARACTERISTICS Specified as Each Channel

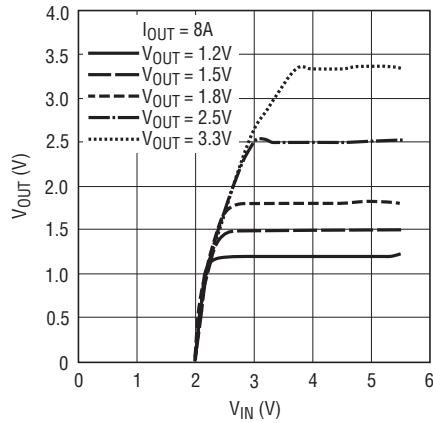


TYPICAL PERFORMANCE CHARACTERISTICS Specified as Each Channel

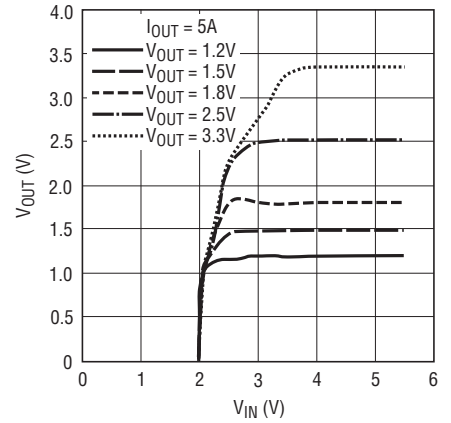
Burst Mode Efficiency with 5V Input



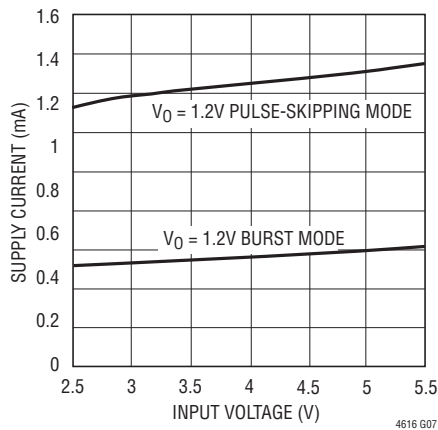
V_{IN} to V_{OUT} Step-Down Ratio



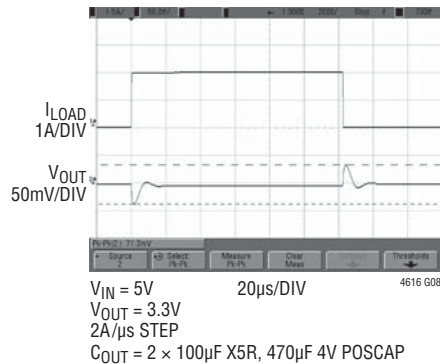
V_{IN} to V_{OUT} Step-Down Ratio



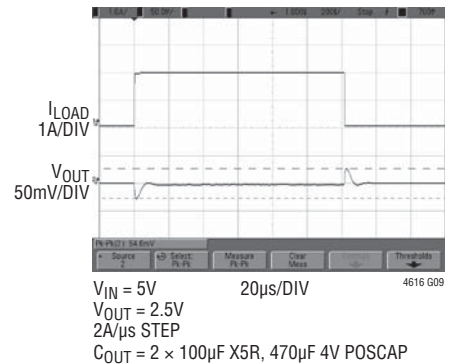
Supply Current vs V_{IN}



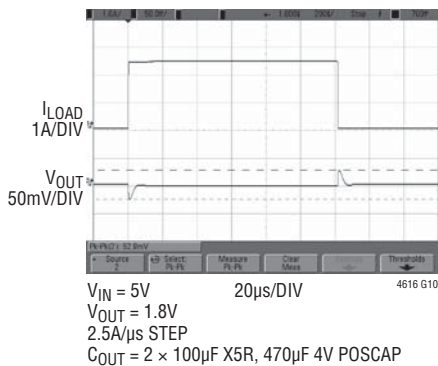
Load Transient Response



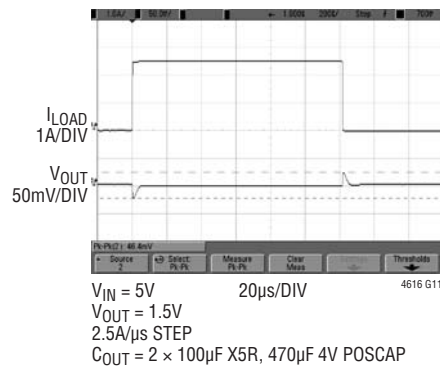
Load Transient Response



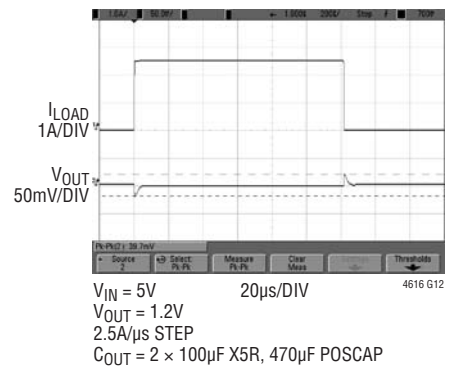
Load Transient Response



Load Transient Response

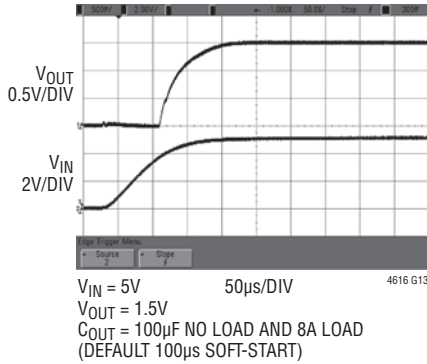


Load Transient Response

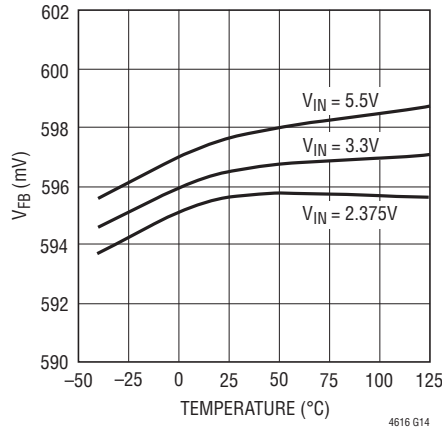


TYPICAL PERFORMANCE CHARACTERISTICS Specified as Each Channel

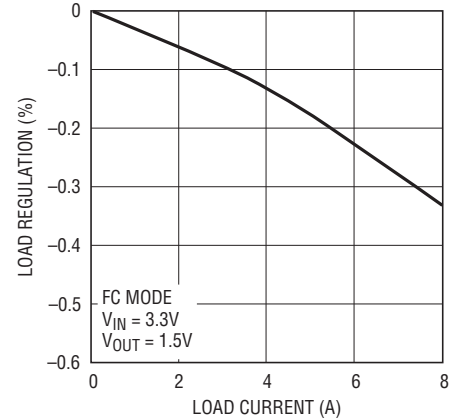
Start-Up



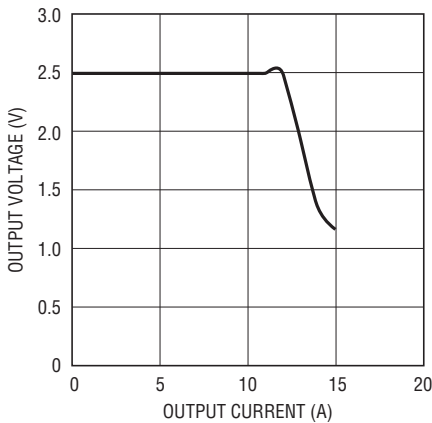
V_{FB} vs Temperature



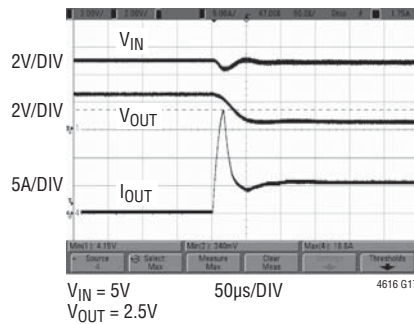
Load Regulation vs Current



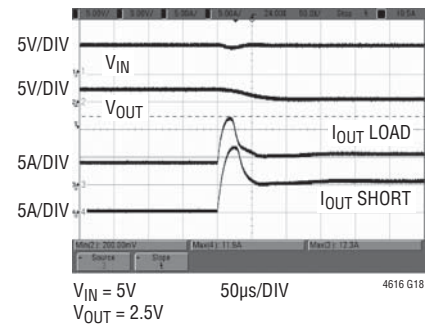
2.5V Output Current



Short-Circuit Protection (2.5V Short, No Load)



Short-Circuit Protection (2.5V Short, 4A Load)



PIN FUNCTIONS

V_{IN1} , V_{IN2} , (BANK1 and BANK2); (F1-F4, E1-E4, C1-C2, D1-D2) and (J1-J2, K1-K2, L1-L4, M1-M4): Power Input Pins. Apply input voltage between these pins and GND pins. Recommend placing input decoupling capacitance directly between V_{IN} pins and GND pins.

V_{OUT1} , V_{OUT2} (BANK3 and BANK6); (D9-D12, E9-E12, F9-F12) and (K9-K12, L9-L12, M9-M12): Power Output Pins. Apply output load between these pins and GND pins. Recommend placing output decoupling capacitance directly between these pins and GND pins. See Table 1.

GND1 and GND2 (BANK2 and BANK5); (A1-A5, A12, B1-B5, B7-B12, C3-C12, D3-D7) and (G1-G5, G12, H1-H5, H7-H12, J3-J12, K3-K7): Power Ground Pins for Both Input and Output Returns.

SV_{IN1} and SV_{IN2} (E5 and L5): Signal Input Voltage for Each Channel. This pin is internally connected to V_{IN} through a lowpass filter.

SGND1 and SGND2 (F5 and M5): Signal Ground Pin for Each Channel. Return ground path for all analog and low power circuitry. Tie a single connection to the output capacitor GND in the application. See layout guidelines in Figure 17.

PIN FUNCTIONS

MODE1 and MODE2 (A8 and G8): Mode Select Input for Each Channel. Tying this pin high enables Burst Mode operation. Tying this pin low enables forced continuous operation. Floating this pin or tying it to $V_{IN}/2$ enables pulse-skipping operation.

CLKIN1 and CLKIN2 (A7 and G7): External Synchronization Input to Phase Detector for Each Channel. This pin is internally terminated to SGND with a 50k resistor. The phase locked loop will force the internal top power PMOS turn on to be synchronized with the rising edge of the CLKIN signal. Connect this pin to SV_{IN} to enable spread spectrum modulation. During external synchronization, make sure the PLLPF pin is not tied to V_{IN} or GND.

PLLLPF1 and PLLPF2 (E6 and L6): Phase Locked Loop Lowpass Filter for Each Channel. An internal lowpass filter is tied to this pin. In spread spectrum mode, placing a capacitor here to SGND controls the slew rate from one frequency to the next. Alternatively, floating this pin allows normal running frequency at 1.5MHz, tying this pin to SV_{IN} forces the part to run at 1.33 times its normal frequency (2MHz), tying it to ground forces the frequency to run at 0.67 times its normal frequency (1MHz).

PHMODE1 and PHMODE2 (A9 and G9): Phase Selector Input for Each Channel. This pin determines the phase relationship between the internal oscillator and CLKOUT. Tie it high for 2-phase operation, tie it low for 3-phase operation, and float or tie it to $V_{IN}/2$ for 4-phase operation.

MGN1 and MGN2 (A10 and G10): Voltage Margining Pin for Each Channel. Tie this pin to V_{OUT} to disable margining. For margining, connect a voltage divider from V_{IN} to GND with the center point connected to the MGN pin for the specific channel. Each resistor should be close to 50k. Margin High is within 0.3V of V_{IN} , and Margin Low is within 0.3V of GND. See the Applications section and Figure 18 for margining control. The specified tri-state drivers are capable of the high and low requirements for margining.

BSEL1 and BSEL2 (A6 and G6): Margining Bit Select Pin for Each Channel. Tying BSEL low selects $\pm 5\%$ margin value, tying it high selects 10% margin value. Floating it or tying it to $V_{IN}/2$ selects 15% margin value.

TRACK1 and TRACK2 (E8 and L8): Output Voltage Track-

ing Pin for Each Channel. Voltage tracking is enabled when the TRACK voltage is below 0.57V. If tracking is not desired, then connect the TRACK pin to SV_{IN} . If TRACK is not tied to SV_{IN} , then the TRACK pin's voltage needs to be below 0.18V before the chip shuts down even though RUN is already low. Do not float this pin. A resistor and capacitor can be applied to the TRACK pin to increase the soft-start time of the regulator. TRACK1 and TRACK2 can be tied together for parallel operation and tracking. See the Applications section.

FB1 and FB2 (D8 and K8): The Negative Input of the Error Amplifier for Each Channel. Internally, this pin is connected to V_{OUT} with a 10k Ω precision resistor. Different output voltages can be programmed with an additional resistor between FB and GND pins. In PolyPhase[®] operation, tying the FB pins together allows for parallel operation. See Applications section for details.

I_{TH1} and I_{TH2} (F8 and M8): Current Control Threshold and Error Amplifier Compensation Point for Each Channel. The current comparator threshold increases with this control voltage. Tie together in parallel operation.

I_{THM1} and I_{THM2} (E7 and L7): Negative Input to the Internal I_{TH} Differential Amplifier for Each Channel. Tie this pin to SGND for single phase operation on each channel. For PolyPhase operation, tie the master's I_{THM} to SGND while connecting all of the I_{THM} pins together at the master.

PGOOD1 and PGOOD2 (A11 and G11): Output Voltage Power Good Indicator for Each Channel. Open-drain logic output that is pulled to ground when the output voltage is not within $\pm 10\%$ of the regulation point. Power good is disabled during margining.

RUN1 and RUN2 (F6 and M6): Run Control Pin. A voltage above 1.5V will turn on the module.

SW1 and SW2 (B6 and H6): Switching Node of Each Channel That is Used for Testing Purposes. This can be connected to copper on the board for improved thermal performance.

CLKOUT1 and CLKOUT2 (F7 and M7): Output Clock Signal for PolyPhase Operation. The phase of CLKOUT is determined by the state of the PHMODE pin.

PolyPhase is a registered trademark of Linear Technology Corporation.

SIMPLIFIED BLOCK DIAGRAM

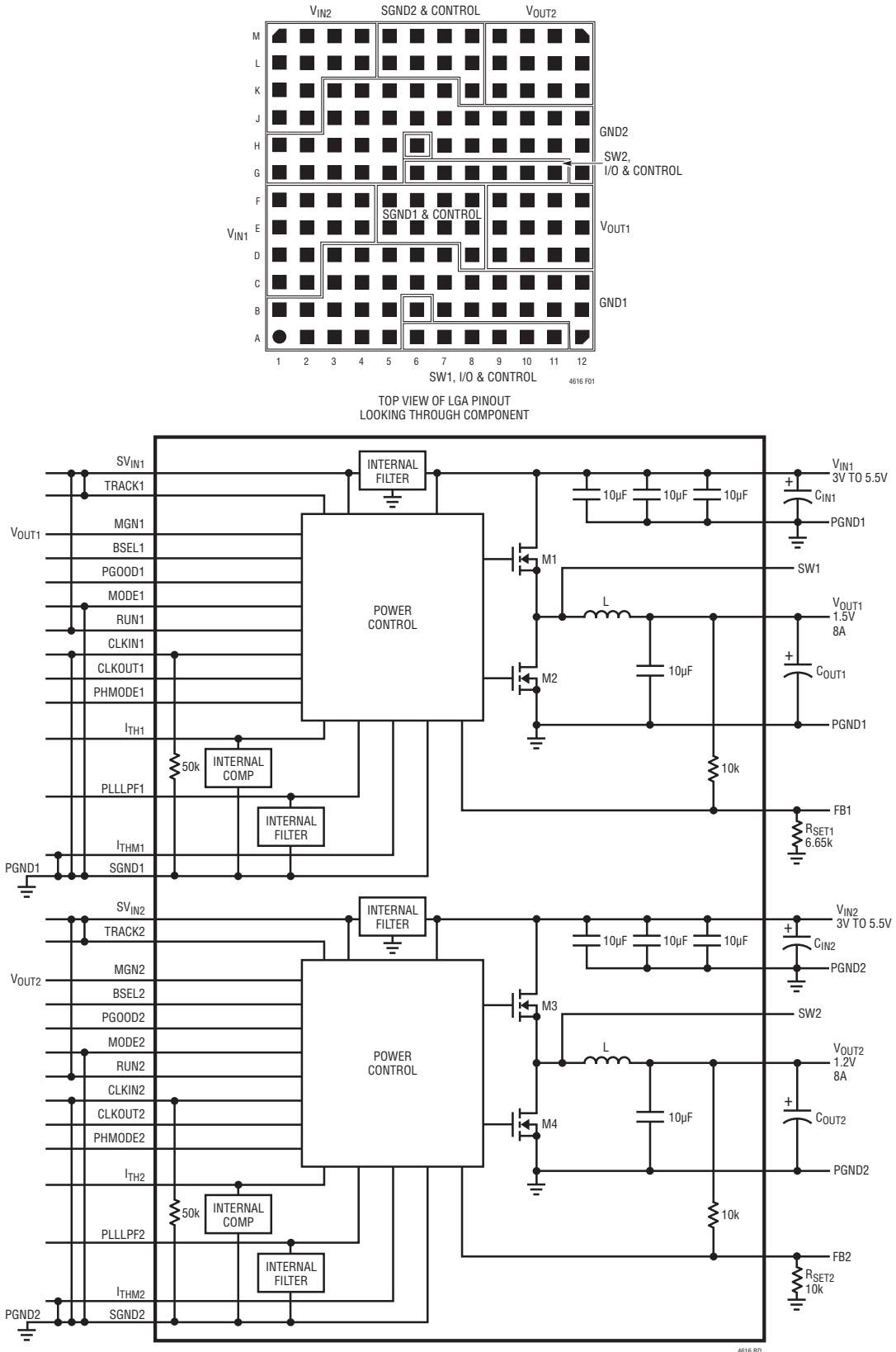


Figure 1. Simplified LTM4616 Block Diagram

SIMPLIFIED BLOCK DIAGRAM

Table 1. Decoupling Requirements. $T_A = 25^\circ\text{C}$, Block Diagram Configuration.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
C_{IN1} C_{IN2}	External Input Capacitor Requirement ($V_{IN1} = 2.375\text{V}$ to 5.5V , $V_{OUT1} = 1.5\text{V}$) ($V_{IN2} = 2.375\text{V}$ to 5.5V , $V_{OUT2} = 2.5\text{V}$)	$I_{OUT1} = 8\text{A}$ $I_{OUT2} = 8\text{A}$		22 22		μF μF
C_{OUT1} C_{OUT2}	External Output Capacitor Requirement ($V_{IN1} = 2.375\text{V}$ to 5.5V , $V_{OUT1} = 1.5\text{V}$) ($V_{IN2} = 2.375\text{V}$ to 5.5V , $V_{OUT2} = 2.5\text{V}$)	$I_{OUT1} = 8\text{A}$ $I_{OUT2} = 8\text{A}$		100 100		μF μF

OPERATION

The LTM4616 is a dual-output standalone nonisolated switching mode DC/DC power supply. It can provide two 8A outputs with few external input and output capacitors. This module provides precisely regulated output voltages programmable via external resistors from $0.6V_{DC}$ to $5V_{DC}$ over 2.375V to 5.5V input voltages. The typical application schematic is shown in Figure 18.

The LTM4616 has integrated constant frequency current mode regulators and built-in power MOSFET devices with fast switching speed. The typical switching frequency is 1.5MHz . For switching noise sensitive applications, it can be externally synchronized from 0.75MHz to 2.25MHz . Even spread spectrum switching can be implemented in the design to reduce noise.

With current mode control and internal feedback loop compensation, the LTM4616 module has sufficient stability margins and good transient performance with a wide range of output capacitors, even with all ceramic output capacitors.

Current mode control provides cycle-by-cycle fast current limit and thermal shutdown in an overcurrent condition. Internal overvoltage and undervoltage comparators pull the open-drain PGOOD output low if the output feedback voltage exits a $\pm 10\%$ window around the regulation point. The power good pins are disabled during margining.

Pulling the RUN pins below 1.3V forces the regulators into a shutdown state, by turning off both MOSFETs. The TRACK pin is used for programming the output voltage ramp and voltage tracking during start-up. See Applications Information section.

The LTM4616 is internally compensated to be stable over all operating conditions. Table 3 provides a guideline for input and output capacitances for several operating conditions. The Linear Technology μModule Power Design Tool will be provided for transient and stability analysis. The FB pin is used to program the output voltage with a single external resistor to ground.

Multiphase operation can be easily employed with the synchronization and phase mode controls. Up to 12 phases can be cascaded to run simultaneously with respect to each other by programming the PHMODE pin to different levels. The LTM4616 has clock in and clock out for poly phasing multiple devices or frequency synchronization.

High efficiency at light loads can be accomplished with selectable Burst Mode operation using the MODE pin. These light load features will accommodate battery operation. Efficiency graphs are provided for light load operation in the Typical Performance Characteristics section.

Output voltage margining is supported, and can be programmed from $\pm 5\%$ to $\pm 15\%$ using the MGN and BSEL pins.

APPLICATIONS INFORMATION

The typical LTM4616 application circuit is shown in Figure 18. External component selection is primarily determined by the maximum load current and output voltage. Refer to Table 3 for specific external capacitor requirements for a particular application.

V_{IN} to V_{OUT} Step-Down Ratios

There are restrictions in the maximum V_{IN} to V_{OUT} step-down ratio that can be achieved for a given input voltage. Each output of the LTM4616 is 100% duty cycle, but the V_{IN} to V_{OUT} minimum drop out is still shown as a function of its load current. For 5V input, all outputs can deliver 8A. For 3.3V input, all outputs can deliver 8A, except 2.5V which is limited to 6A. All outputs derived from 2.5V are limited to 6A.

Output Voltage Programming

The PWM controller has an internal 0.596V reference voltage. As shown in the Block Diagram, a 10k Ω 0.5% internal feedback resistor connects V_{OUT} and FB pins together. The output voltage will default to 0.596V with no feedback resistor. Adding a resistor R_{FB} from FB pin to GND programs the output voltage:

$$V_{OUT} = 0.596V \cdot \frac{10k + R_{FB}}{R_{FB}}$$

Table 2. FB Resistor vs Various Output Voltages

V_{OUT}	0.596V	1.2V	1.5V	1.8V	2.5V	3.3V
R_{FB}	Open	10k	6.65k	4.87k	3.09k	2.21k

For parallel operation of N the below equation can be used to solve for R_{FB} : Tying the FB pins together for each parallel output.

$$R_{FB} = \frac{10k / N}{\frac{V_{OUT}}{0.596} - 1}$$

Input Capacitors

The LTM4616 module should be connected to a low AC impedance DC source. For each regulator, three 10 μ F ceramic capacitors are included inside the module. Additional input capacitors are only needed if a large load

step is required up to the 4A level. A 47 μ F to 100 μ F surface mount aluminum electrolytic bulk capacitor can be used for more input bulk capacitance. This bulk input capacitor is only needed if the input source impedance is compromised by long inductive leads, traces or not enough source capacitance. If low impedance power planes are used, then this 47 μ F capacitor is not needed.

For a buck converter, the switching duty-cycle can be estimated as:

$$D = \frac{V_{OUT}}{V_{IN}}$$

Without considering the inductor current ripple, the RMS current of the input capacitor can be estimated as:

$$I_{CIN(RMS)} = \frac{I_{OUT(MAX)}}{\eta\%} \cdot \sqrt{D \cdot (1-D)}$$

In the above equation, $\eta\%$ is the estimated efficiency of the power module so the RMS input current at the worst case for 8A maximum current is about 4A. The bulk capacitor can be a switcher-rated electrolytic aluminum capacitor, polymer capacitor for bulk input capacitance. Each internal 10 μ F ceramic input capacitor is typically rated for 2 amps of RMS ripple current.

Output Capacitors

The LTM4616 is designed for low output voltage ripple noise. The bulk output capacitors defined as C_{OUT} are chosen with low enough effective series resistance (ESR) to meet the output voltage ripple and transient requirements. C_{OUT} can be a low ESR tantalum capacitor, low ESR polymer capacitor or ceramic capacitor. The typical output capacitance range is from 47 μ F to 220 μ F. Additional output filtering may be required by the system designer, if further reduction of output ripples or dynamic transient spikes is required. Table 3 shows a matrix of different output voltages and output capacitors to minimize the voltage droop and overshoot during a 3A/ μ s transient. The table optimizes total equivalent ESR and total bulk capacitance to optimize the transient performance. Stability criteria are considered in the Table 3 matrix, and the Linear Technology μ Module Power Design Tool will be provided for stability analysis.

APPLICATIONS INFORMATION

Table 3. Output Voltage Response Versus Component Matrix (Refer to Figure 18) 0A to 3A Load Step

TYPICAL MEASURED VALUES													
C _{OUT1} VENDORS		VALUE	PART NUMBER		C _{OUT2} VENDORS		VALUE	PART NUMBER					
TDK		22μF, 6.3V	C3216X7S0J226M		Sanyo POSCAP		470μF, 4V	4TPE470M					
Murata		22μF, 16V	GRM31CR61C226KE15L		C _{IN} (BULK) VENDORS		VALUE	PART NUMBER					
TDK		100μF, 6.3V	C4532X5R0J107MZ		Sanyo		100μF, 10V	10CE100FH					
Murata		100μF, 6.3V	GRM32ER60J107M										

V _{OUT} (V)	C _{IN} (CERAMIC)	C _{IN} (BULK)*	C _{OUT1} (CERAMIC)	C _{OUT2} (BULK)	I _{TH}	C1	C3	V _{IN} (V)	DROOP (mV)	PEAK-TO-PEAK DEVIATION (mV)	RECOVERY TIME (μs)	LOAD STEP (A/μs)	R _{FB} (kΩ)
1.0	10μF	100μF	100μF × 2	470μF	None	None	None	5	20	40	40	2.5	14.7
1.0	10μF	100μF	100μF × 2		None	None	None	5	30	60	25	2.5	14.7
1.0	10μF	100μF	100μF × 2		None	None	None	2.5	30	60	25	2.5	14.7
1.0	10μF	100μF	22μF × 1	470μF	None	None	None	2.5	25	50	25	2.5	14.7
1.2	10μF	100μF	100μF × 2		None	None	None	5	20	40	25	2.5	10
1.2	10μF	100μF	22μF × 1	470μF	None	None	None	5	20	41	25	2.5	10
1.2	10μF	100μF	100μF × 2		None	None	None	2.5	30	60	20	2.5	10
1.2	10μF	100μF	22μF × 1	470μF	None	None	None	2.5	30	60	25	2.5	10
1.5	10μF	100μF	100μF × 2		None	None	None	5	32	64	20	2.5	6.65
1.5	10μF	100μF	22μF × 1	470μF	None	None	None	5	25	50	25	2.5	6.65
1.5	10μF	100μF	100μF × 1		None	None	None	3.3	22	42	25	2.5	6.65
1.5	10μF	100μF	22μF × 1	470μF	None	None	None	3.3	25	50	25	2.5	6.65
1.5	10μF	100μF	100μF × 2		None	None	None	2.5	30	60	25	2.5	6.65
1.5	10μF	100μF	22μF × 1	470μF	None	None	None	2.5	25	50	25	2.5	6.65
1.8	10μF	100μF	100μF × 1		None	None	None	5	42	80	25	2.5	4.87
1.8	10μF	100μF	22μF × 1	470μF	None	None	None	5	25	50	30	2.5	4.87
1.8	10μF	100μF	100μF × 2		None	None	None	3.3	35	70	30	2.5	4.87
1.8	10μF	100μF	22μF × 1	470μF	None	None	None	3.3	25	50	30	2.5	4.87
1.8	10μF	100μF	100μF × 2		None	None	None	2.5	35	70	30	2.5	4.87
1.8	10μF	100μF	22μF × 1	470μF	None	None	None	2.5	35	20	30	2.5	4.87
2.5	10μF	100μF	100μF × 1		None	None	None	5	35	40	30	2.5	3.09
2.5	10μF	100μF	22μF × 1	470μF	None	None	None	5	32	65	40	2.5	3.09
2.5	10μF	100μF	100μF × 1		None	None	None	3.3	50	100	30	2.5	3.09
2.5	10μF	100μF	22μF × 1	470μF	None	None	None	3.3	32	65	40	2.5	3.09
3.3	10μF	100μF	100μF × 1		None	None	None	5	65	135	30	2.5	2.21
3.3	10μF	100μF	22μF × 1	470μF	None	None	None	5	40	87	40	2.5	2.21

*Bulk capacitance is optional if V_{IN} has very low input impedance.

Multiphase operation will reduce effective output ripple as a function of the number of phases. Application Note 77 discusses this noise reduction versus output ripple current cancellation, but the output capacitance will be more a function of stability and transient response. The Linear Technology μModule Power Design Tool will calculate the output ripple reduction as the phase number increases by N times.

Burst Mode Operation

The LTM4616 is capable of Burst Mode operation on each regulator in which the power MOSFETs operate intermittently based on load demand, thus saving quiescent current. For applications where maximizing the efficiency at very light loads is a high priority, Burst Mode operation should be applied. To enable Burst Mode operation, simply tie the MODE pin to V_{IN}. During this operation, the peak current of the inductor is set to approximately 20%

APPLICATIONS INFORMATION

of the maximum peak current value in normal operation even though the voltage at the I_{TH} pin indicates a lower value. The voltage at the I_{TH} pin drops when the inductor's average current is greater than the load requirement. As the I_{TH} voltage drops below 0.2V, the BURST comparator trips, causing the internal sleep line to go high and turn off both power MOSFETs.

In Burst Mode operation, the internal circuitry is partially turned off, reducing the quiescent current to about 450 μ A for each output. The load current is now being supplied from the output capacitors. When the output voltage drops, causing I_{TH} to rise above 0.25V, the internal sleep line goes low, and the LTM4616 resumes normal operation. The next oscillator cycle will turn on the top power MOSFET and the switching cycle repeats. Each regulator can be configured for Burst Mode operation.

Pulse-Skipping Mode Operation

In applications where low output ripple and high efficiency at intermediate currents are desired, pulse-skipping mode should be used. Pulse-skipping operation allows the LTM4616 to skip cycles at low output loads, thus increasing efficiency by reducing switching loss. Floating the MODE pin or tying it to $V_{IN}/2$ enables pulse-skipping operation. This allows discontinuous conduction mode (DCM) operation down to near the limit defined by the chip's minimum on-time (about 100ns). Below this output current level, the converter will begin to skip cycles in order to maintain output regulation. Increasing the output load current slightly, above the minimum required for discontinuous conduction mode, allows constant frequency PWM. Each regulator can be configured for Pulse-Skipping mode.

Forced Continuous Operation

In applications where fixed frequency operation is more critical than low current efficiency, and where the lowest output ripple is desired, forced continuous operation should be used. Forced continuous operation can be enabled by tying the MODE pin to GND. In this mode, inductor current is allowed to reverse during low output loads, the I_{TH} voltage is in control of the current comparator threshold throughout, and the top MOSFET always turns on with each oscillator pulse. During start-up, forced continu-

ous mode is disabled and inductor current is prevented from reversing until the LTM4616's output voltage is in regulation. Each regulator can be configured for Force Continuous mode.

Multiphase Operation

For output loads that demand more than 8A of current, two outputs in LTM4616 or even multiple LTM4616s can be cascaded to run out of phase to provide more output current without increasing input and output voltage ripples. The CLKIN pin allows the LTM4616 to synchronize to an external clock (between 0.75MHz and 2.25MHz) and the internal phase locked loop allows the LTM4616 to lock onto CLKIN's phase as well. The CLKOUT signal can be connected to the CLKIN pin of the following LTM4616 stage to line up both the frequency and the phase of the entire system. Tying the PHMODE pin to SV_{IN} , SGND or $SV_{IN}/2$ (floating) generates a phase difference (between CLKIN and CLKOUT) of 180°, 120° or 90° respectively, which corresponds to a 2-phase, 3-phase or 4-phase operation. A total of 12 phases can be cascaded to run simultaneously with respect to each other by programming the PHMODE pin of each LTM4616 to different levels. For a 6-phase example in Figure 2, the 2nd stage that is 120° out of phase from the 1st stage can generate a 240° (PHMODE = 0) CLKOUT signal for the 3rd stage, which then can generate a CLKOUT signal that's 420°, or 60° (PHMODE = SV_{IN}) for the 4th stage. With the 60° CLKIN input, the next two stages can shift 120° (PHMODE = 0) for each to generate a 300° signal for the 6th stage. Finally, the signal with a 60° phase shift on the 6th stage (PHMODE is floating) goes back to the 1st stage. Figure 3 shows the configuration for 12-phase operation.

A multiphase power supply significantly reduces the amount of ripple current in both the input and output capacitors. The RMS input ripple current is reduced by, and the effective ripple frequency is multiplied by, the number of phases used (assuming that the input voltage is greater than the number of phases used times the output voltage). The output ripple amplitude is also reduced by the number of phases used.

The LTM4616 device is an inherently current mode controlled device, so parallel modules will have very good

APPLICATIONS INFORMATION

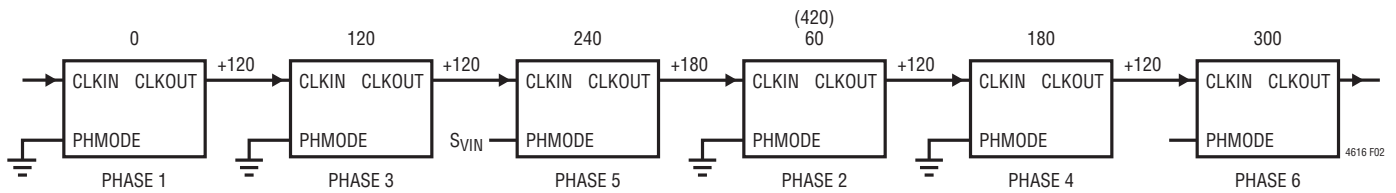


Figure 2. 6-Phase Operation

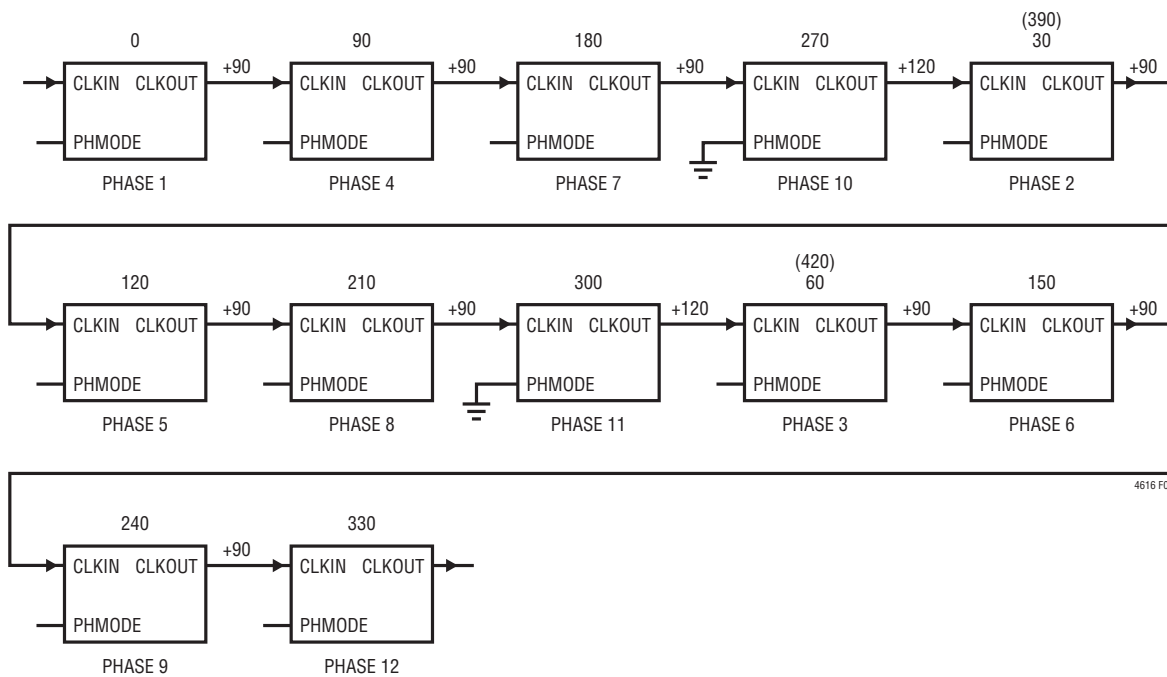


Figure 3. 12-Phase Operation

current sharing. This will balance the thermals on the design. Tie the I_{TH} pins of each LTM4616 together to share the current evenly. To reduce ground potential noise, tie the I_{THM} pins of all LTM4616s together and then connect to the SGND of the master at the point it connects to the output capacitor GND. See layout guideline in Figure 17. Figure 19 shows a schematic of the parallel design. The FB pins of the parallel module are tied together.

Input RMS Ripple Current Cancellation

Application Note 77 provides a detailed explanation of multiphase operation. The input RMS ripple current cancellation mathematical derivations are presented, and a graph is displayed representing the RMS ripple current reduction as a function of the number of interleaved phases. Figure 4 shows this graph.

Spread Spectrum Operation

Switching regulators can be particularly troublesome where electromagnetic interference (EMI) is concerned.

Switching regulators operate on a cycle-by-cycle basis to transfer power to an output. In most cases, the frequency of operation is fixed based on the output load. This method of conversion creates large components of noise at the frequency of operation (fundamental) and multiples of the operating frequency (harmonics).

To reduce this noise, the LTM4616 can run in spread spectrum operation by tying the CLKIN pin to SV_{IN} . In spread spectrum operation, the LTM4616's internal oscillator is designed to produce a clock pulse whose period is random on a cycle-by-cycle basis but fixed

APPLICATIONS INFORMATION

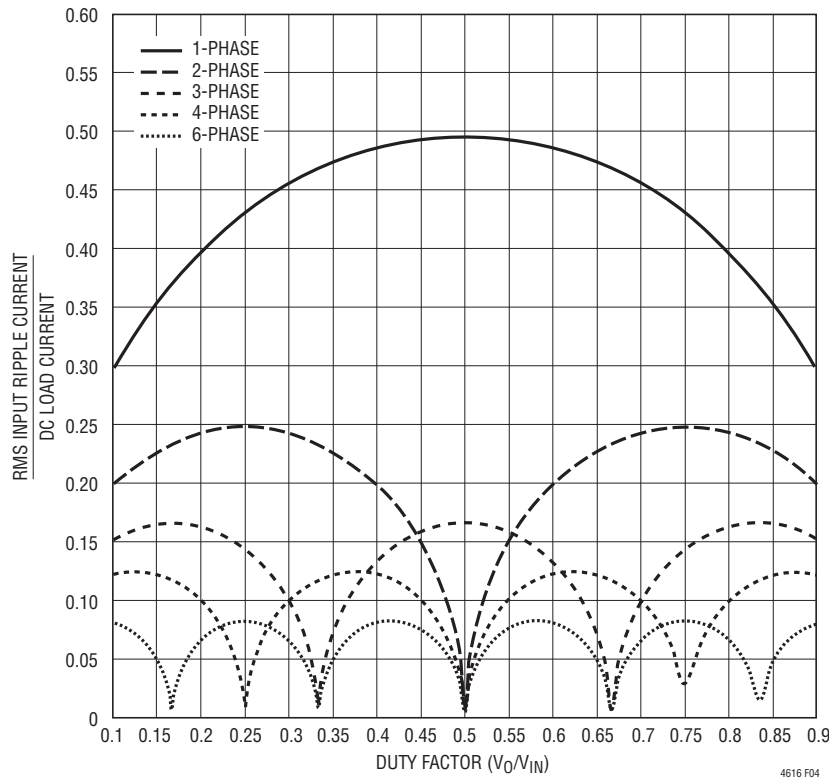


Figure 4. Normalized Input RMS Ripple Current vs Duty Factor for One to Six Channels (Phases)

between 70% and 130% of the nominal frequency. This has the benefit of spreading the switching noise over a range of frequencies, thus significantly reducing the peak noise. Spread spectrum operation is disabled if CLKIN is tied to ground or if it's driven by an external frequency synchronization signal. A capacitor value of 0.01 μ F to 0.1 μ F be placed from the PLLPF pin to ground to control the slew rate of the spread spectrum frequency change.

Output Voltage Tracking

Output voltage tracking can be programmed externally using the TRACK pin. The output can be tracked up and down with another regulator. The master regulator's output is divided down with an external resistor divider that is the same as the slave regulator's feedback divider to implement coincident tracking. The LTM4616 uses an accurate 10k resistor internally for the top feedback resistor. Figure 5 shows an example of coincident tracking:

$$\text{Slave} = \left(1 + \frac{10\text{k}}{R_{TA}}\right) \cdot V_{\text{TRACK}}$$

V_{TRACK} is the track ramp applied to the slave's track pin. V_{TRACK} has a control range of 0V to 0.596V, or the internal reference voltage. When the Master's output is divided down with the same resistor values used to set the slave's output, then the slave will coincident track with the master until it reaches its final value. The master will continue to its final value from the slave's regulation point. Voltage tracking is disabled when V_{TRACK} is more than 0.596V. R_{TA} in Figure 5 will be equal to R_{FB} for coincident tracking.

The track pin of the master can be controlled by an external ramp or by R_{SR} and C_{SR} in Figure 5 referenced to V_{IN} . The RC ramp time can be programmed using equation:

$$t = -\left(\ln\left(1 - \frac{0.596\text{V}}{V_{IN}}\right) \cdot R_{SR} \cdot C_{SR}\right)$$

Ratiometric tracking can be achieved by a few simple calculations and the slew rate value applied to the master's track pin. As mentioned above, the TRACK pin has a control range from 0V to 0.596V. The master's TRACK pin slew

APPLICATIONS INFORMATION

rate is directly equal to the master's output slew rate in Volts/Time:

$$\frac{MR}{SR} \cdot 10k = R_{TB}$$

where MR is the master's output slew rate and SR is the slave's output slew rate in Volts/Time. When coincident tracking is desired, then MR and SR are equal, thus R_{TB} is equal to 10k. R_{TA} is derived from equation:

$$R_{TA} = \frac{0.596V}{\frac{V_{FB}}{10k} + \frac{V_{FB}}{R_{FB}} - \frac{V_{TRACK}}{R_{TB}}}$$

where V_{FB} is the feedback voltage reference of the regulator and V_{TRACK} is 0.596V. Since R_{TB} is equal to the 10k top feedback resistor of the slave regulator in equal slew rate or coincident tracking, then R_{TA} is equal to R_{TB} with $V_{FB} = V_{TRACK}$. Therefore $R_{TB} = 10k$ and $R_{TA} = 6.65k$ in Figure 5. Figure 6 shows the output voltage for coincident tracking.

In ratiometric tracking, a different slew rate maybe desired for the slave regulator. R_{TB} can be solved for when SR is slower than MR. Make sure that the slave supply slew rate is chosen to be fast enough so that the slave output voltage will reach it final value before the master output.

For example: MR = 3.3V/ms and SR = 1.5V/ms. Then $R_{TB} = 22.1k$. Solve for R_{TA} to equal to 4.87k.

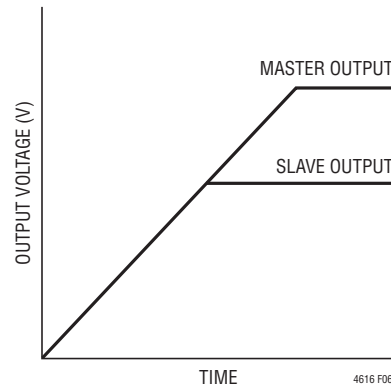
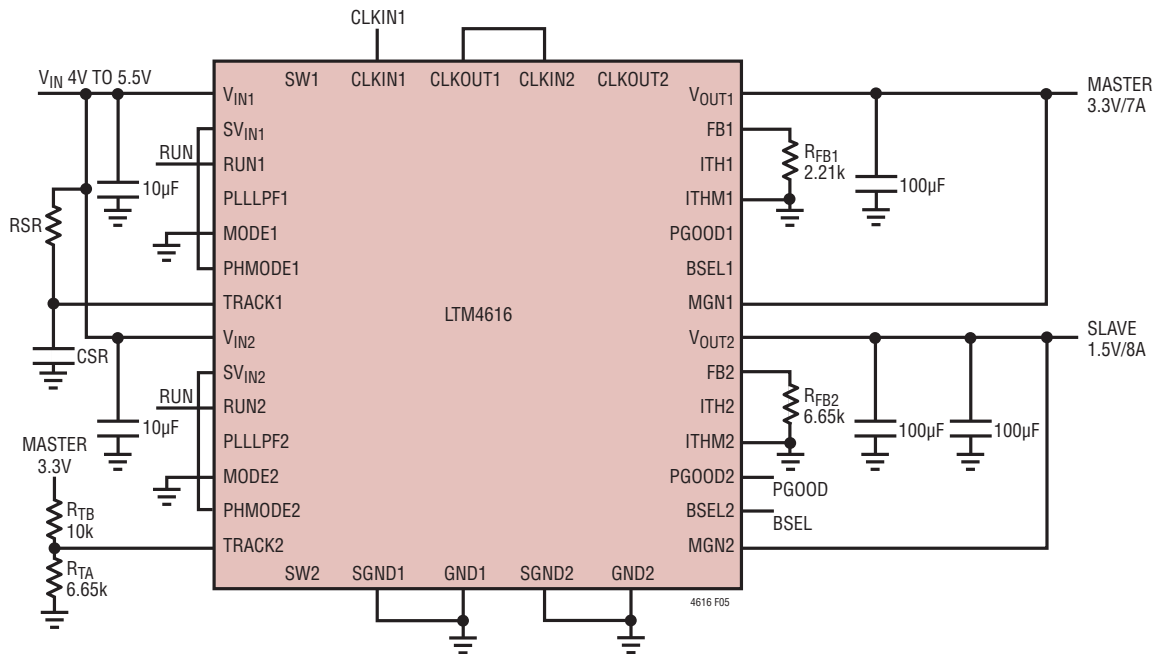


Figure 6. Output Voltage Coincident Tracking



- FOR TRACK1:
1. TIE TO VIN TO DISABLE TRACK WITH DEFAULT 100µs SOFT START
 2. APPLY A CONTROL RAMP WITH RSR AND CSR TIED TO VIN WITH $t = -(\ln(1 - 0.596/V_{IN}) \cdot RSR \cdot CSR)$
 3. APPLY AN EXTERNAL TRACKING RAMP DIRECTLY

Figure 5. Dual Outputs (3.3V and 1.5V) with Tracking

APPLICATIONS INFORMATION

For applications that do not require tracking or sequencing, simply tie the TRACK pin to SV_{IN} to let RUN control the turn on/off. Connecting TRACK to SV_{IN} also enables the $\sim 100\mu s$ of internal soft-start during start-up.

Power Good

The PGOOD pin is an open-drain pin that can be used to monitor valid output voltage regulation. This pin monitors a $\pm 10\%$ window around the regulation point. As shown in Figure 20, the sequencing function can be realized in a dual output application by controlling the RUN pins and the PGOOD signals from each other. The 1.5V output begins its soft starting after the PGOOD signal of 3.3V output becomes high, and 3.3V output starts its shut down after the PGOOD signal of 1.5V output becomes low. This can be applied to systems that require voltage sequencing between the core and sub-power supplies.

Stability Compensation

The module has already been internally compensated for all output voltages. Table 2 is provided for most application requirements. The Linear Technology μ Module Power Design Tool will be provided for other control loop optimization.

Output Margining

For a convenient system stress test on the LTM4616's output, the user can program each output to $\pm 5\%$, $\pm 10\%$ or $\pm 15\%$ of its normal operational voltage. The MGN pin is tied to the output voltage to disable margining. When the

MGN pin is low, it forces negative margining, in which the output voltage is below the regulation point. When MGN is high, the output voltage is forced to above the regulation point. The MGN pin with a voltage divider is driven with a small tri-state gate as shown in Figure 18 for three margin states, (High, Low, and No Margin). The amount of output voltage margining is determined by the BSEL pin. When BSEL is low, it's 5%. When BSEL is high, it's 10%. When BSEL is floating, it's 15%. When margining is active, the internal output overvoltage and undervoltage comparators are disabled and PGOOD remains high.

Thermal Considerations and Output Current Derating

The power loss curves in Figures 7 and 8 can be used in coordination with the load current derating curves in Figures 9 to 16 for calculating an approximate θ_{JA} thermal resistance for the LTM4616 with various heatsinking and airflow conditions. Both LTM4616 outputs are placed in parallel for a total output current of 16A, and the power loss curves are plotted for specific output voltages up to 16A. The derating curves are plotted with each output at 8A combined for a total of 16A. The output voltages are 1.2V, 2.5V and 3.3V. These are chosen to include the lower and higher output voltage ranges for correlating the thermal resistance. Thermal models are derived from several temperature measurements in a controlled temperature chamber along with thermal modeling analysis. The junction temperatures are monitored while ambient temperature increased with and without airflow. The junctions are maintained at $\sim 115^\circ C$ while lowering output current or

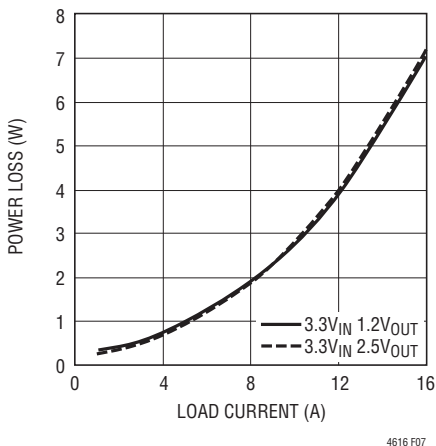


Figure 7. 1.2V, 2.5V Power Loss

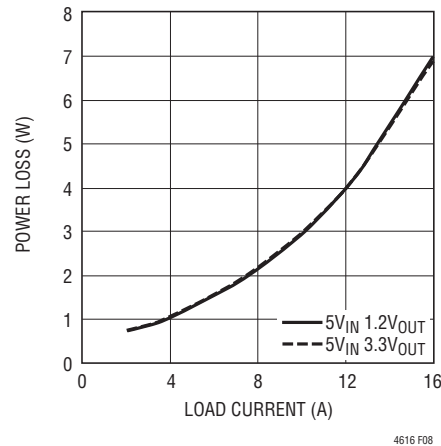
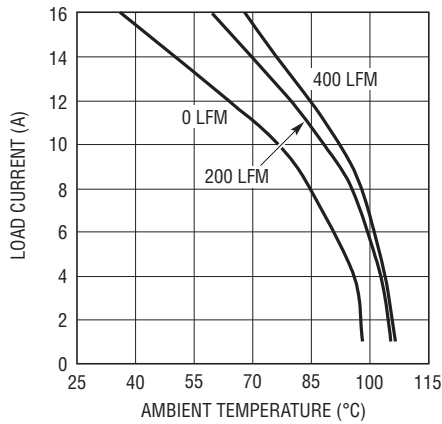


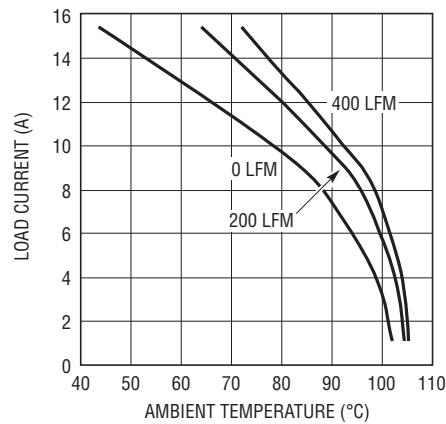
Figure 8. 1.2V, 3.3V Power Loss

APPLICATIONS INFORMATION



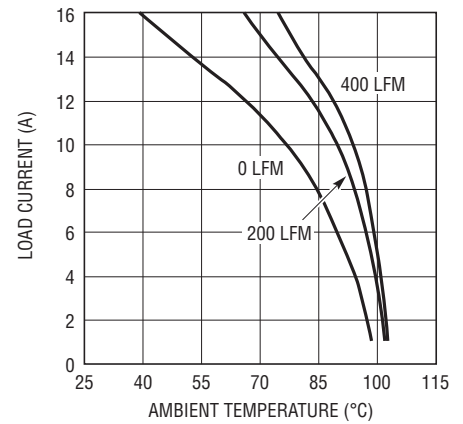
4616 F09

Figure 9. 5V_{IN} to 3.3V_{OUT} with No Heatsink



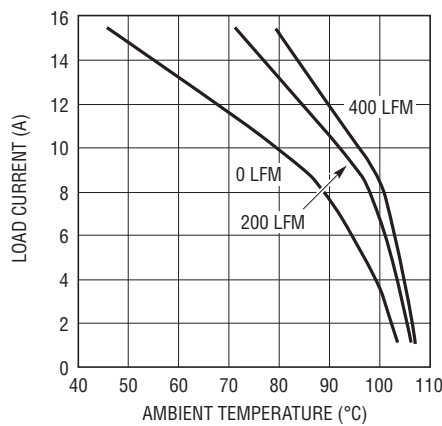
4616 F10

Figure 10. 5V_{IN} to 1.2V_{OUT} with No Heatsink



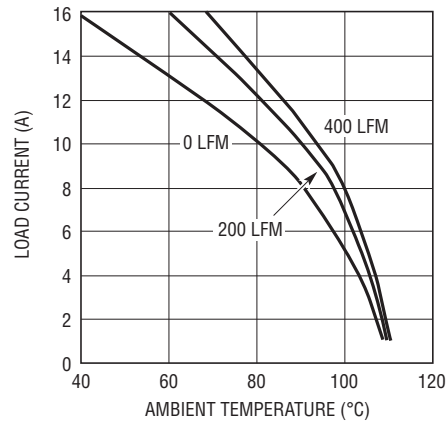
4616 F11

Figure 11. 5V_{IN} to 3.3V_{OUT} with BGA Heatsink



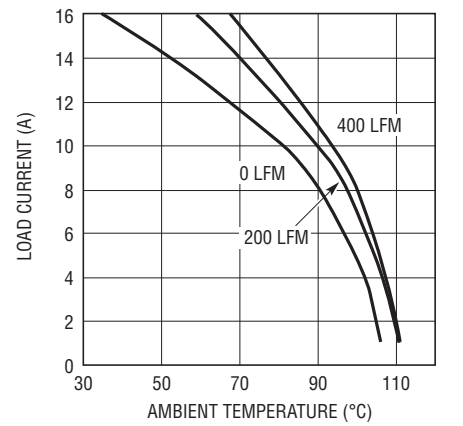
4616 F12

Figure 12. 5V_{IN} to 1.2V_{OUT} with BGA Heatsink



4616 F13

Figure 13. 3.3V_{IN} to 1.2V_{OUT} with No Heatsink



4616 F14

Figure 14. 3.3V_{IN} to 2.5V_{OUT} with No Heatsink

power while increasing ambient temperature. The 115°C is chosen to allow for a 10°C margin window relative to the maximum 125°C. The decreased output current will decrease the internal module loss as ambient temperature is increased. The power loss curves in Figures 7 and 8 show this amount of power loss as a function of load current that is specified with both channels in parallel. The monitored junction temperature of 115°C minus the ambient operating temperature specifies how much module temperature rise can be allowed. As an example, in Figure 10 the load current is derated to 10A at ~80°C and the power loss for the 5V to 1.2V at 10A output is ~3W. If the 80°C ambient temperature is subtracted from the 115°C maximum junction temperature, then difference of 35°C divided by 3.2W equals a 10.9°C/W. Table 4 specifies

a 10.5°C/W value which is very close. Table 4 and Table 5 provide equivalent thermal resistances for 1.2V and 3.3V outputs, with and without airflow and heatsinking. The printed circuit board is a 1.6mm thick four layer board with two ounce copper for the two outer layers and 1 ounce copper for the two inner layers. The PCB dimensions are 95mm × 76mm. The BGA heatsinks are listed below Table 5. At load currents on each channel from 3A to 8A (6A to 16A in parallel on the derate curves); the thermal resistance values in Tables 4 and 5 are closely accurate. As the load currents go below the 3A level on each channel the thermal resistance starts to increase due to the reduced power loss on the board. The approximate thermal resistance values for these lower currents is 15°C/W.

4616f

APPLICATIONS INFORMATION

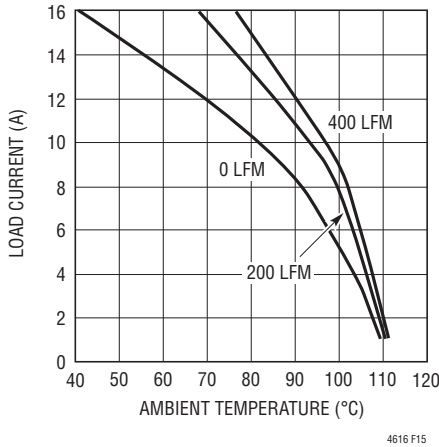


Figure 15. 3.3V_{IN} 1.2V_{OUT} with BGA Heatsink

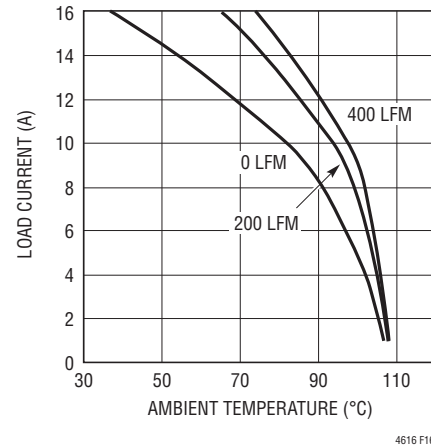


Figure 16. 3.3V_{IN} 2.5V_{OUT} with BGA Heatsink

Table 4. 1.2V Output

DERATING CURVE	V _{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	θ _{JA} (°C/W)
Figures 10, 13	3.3, 5	Figures 7, 8	0	None	10.5
Figures 10, 13	3.3, 5	Figures 7, 8	200	None	8.0
Figures 10, 13	3.3, 5	Figures 7, 8	400	None	7.0
Figures 12, 15	3.3, 5	Figures 7, 8	0	BGA Heat Sink	9.5
Figures 12, 15	3.3, 5	Figures 7, 8	200	BGA Heat Sink	6.3
Figures 12, 15	3.3, 5	Figures 7, 8	400	BGA Heat Sink	5.2

Table 5. 3.3V Output

DERATING CURVE	V _{IN} (V)	POWER LOSS CURVE	AIR FLOW (LFM)	HEAT SINK	θ _{JA} (°C/W)
Figure 9	5	Figure 8	0	None	10.5
Figure 9	5	Figure 8	200	None	8.0
Figure 9	5	Figure 8	400	None	7.0
Figure 11	5	Figure 8	0	BGA Heat Sink	9.8
Figure 11	5	Figure 8	200	BGA Heat Sink	7.0
Figure 11	5	Figure 8	400	BGA Heat Sink	5.5

Heatsink Manufacturer

Wakefield Engineering	Part No: LTN20069	Phone Number: 603-635-2800
AAVID Thermalloy	Part No: 375424B000346	Phone Number: 603-224-9988

Safety Considerations

The LTM4616 modules do not provide isolation from V_{IN} to V_{OUT}. There is no internal fuse. If required, a slow blow fuse with a rating twice the maximum input current needs to be provided to protect each unit from catastrophic failure. The device does support thermal shutdown and over current protection.

Layout Checklist/Example

The high integration of LTM4616 makes the PCB board layout very simple and easy. However, to optimize its electrical and thermal performance, some layout considerations are still necessary.

- Use large PCB copper areas for high current paths, including V_{IN1}, V_{IN2}, PGND1 and PGND2, V_{OUT1} and V_{OUT2}. It helps to minimize the PCB conduction loss and thermal stress.

APPLICATIONS INFORMATION

- Place high frequency ceramic input and output capacitors next to the V_{IN} , GND and V_{OUT} pins to minimize high frequency noise.
- Place a dedicated power ground layer underneath the unit.
- To minimize the via conduction loss and reduce module thermal stress, use multiple vias for interconnection between top layer and other power layers.
- Do not put vias directly on the pads, unless they are capped or plated over.
- Use a separated SGND ground copper area for components connected to signal pins. Connect the SGND to GND underneath the unit.
- For parallel modules, tie the I_{TH} , FB and I_{THM} pins together. Use an internal layer to closely connect these pins together. All of the I_{THM} pins connect to the SGND of the master regulator, then the master SGND connects to GND.

Figure 17 gives a good example of the recommended layout.

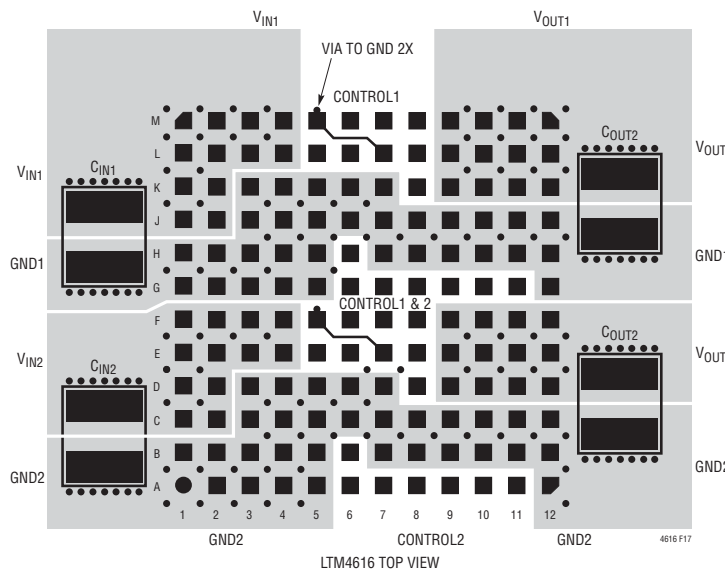
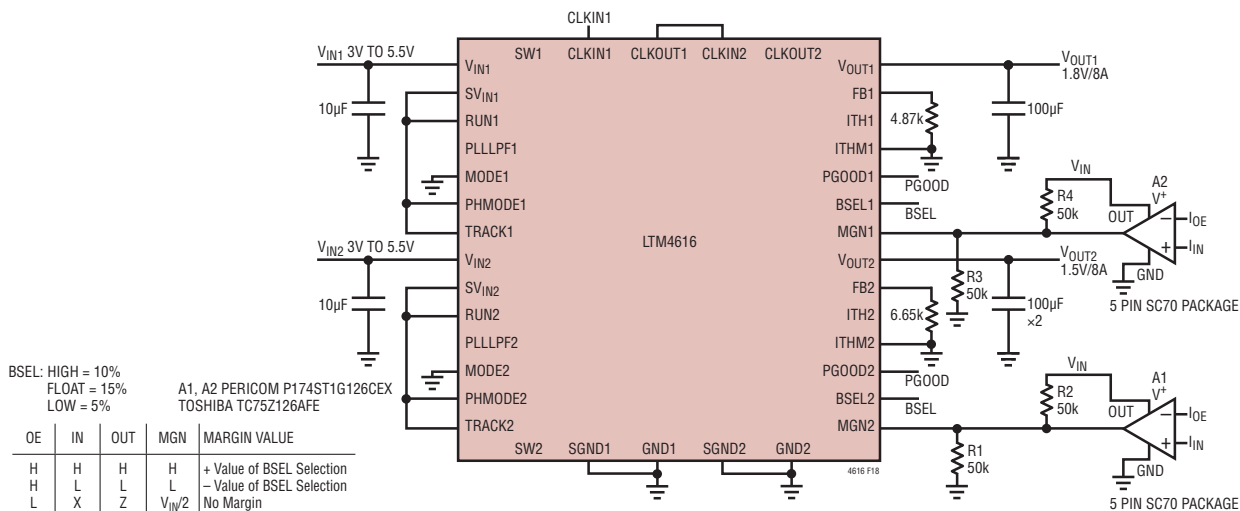


Figure 17. Recommended PCB Layout



BSEL: HIGH = 10%
 FLOAT = 15%
 LOW = 5%

A1, A2 PERICOM P174ST1G126CEX
 TOSHIBA TC75Z126AFE

OE	IN	OUT	MGN	MARGIN VALUE
H	H	H	H	+ Value of BSEL Selection
H	L	L	L	- Value of BSEL Selection
L	X	Z	$V_{IN}/2$	No Margin

Figure 18. Typical 3.2V to 5V_{VIN}, to 1.8V, 1.5V Outputs

APPLICATIONS INFORMATION

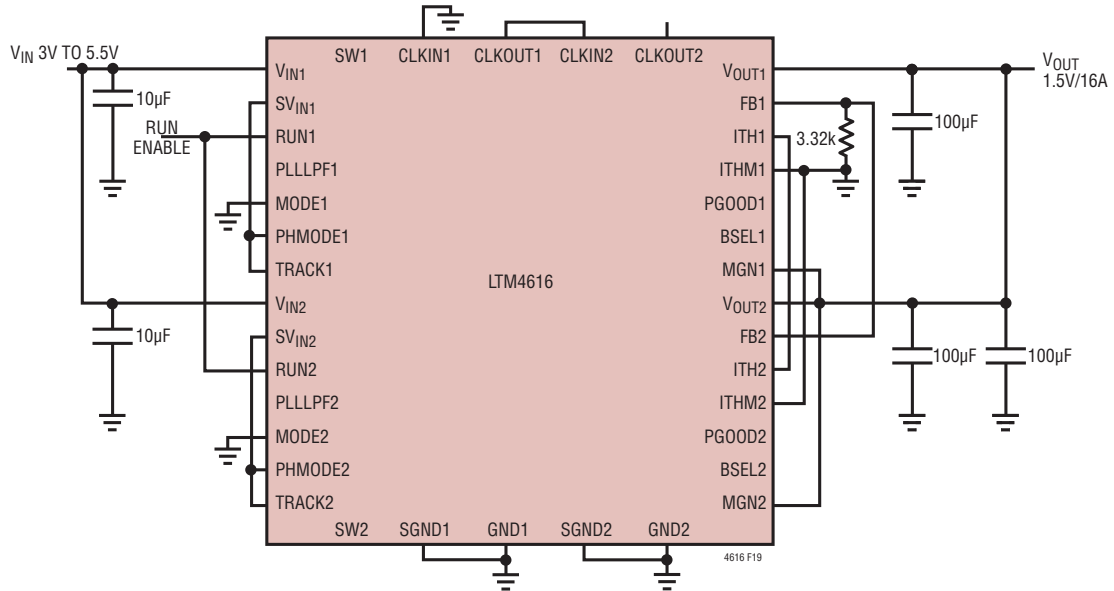


Figure 19. LTM4616 Two Outputs Parallel, 1.5V at 16A Design

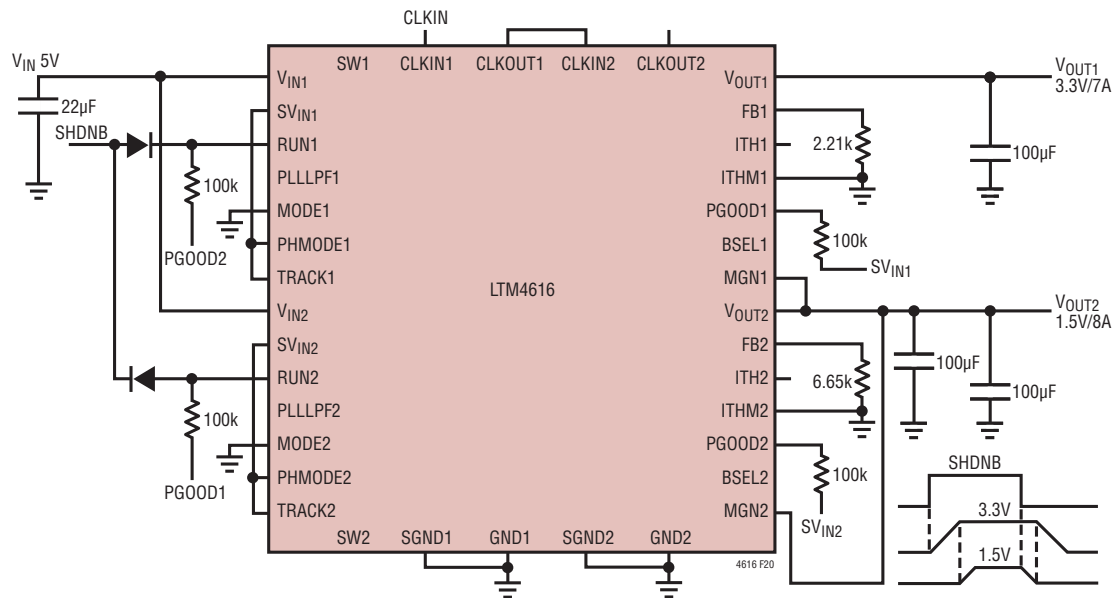
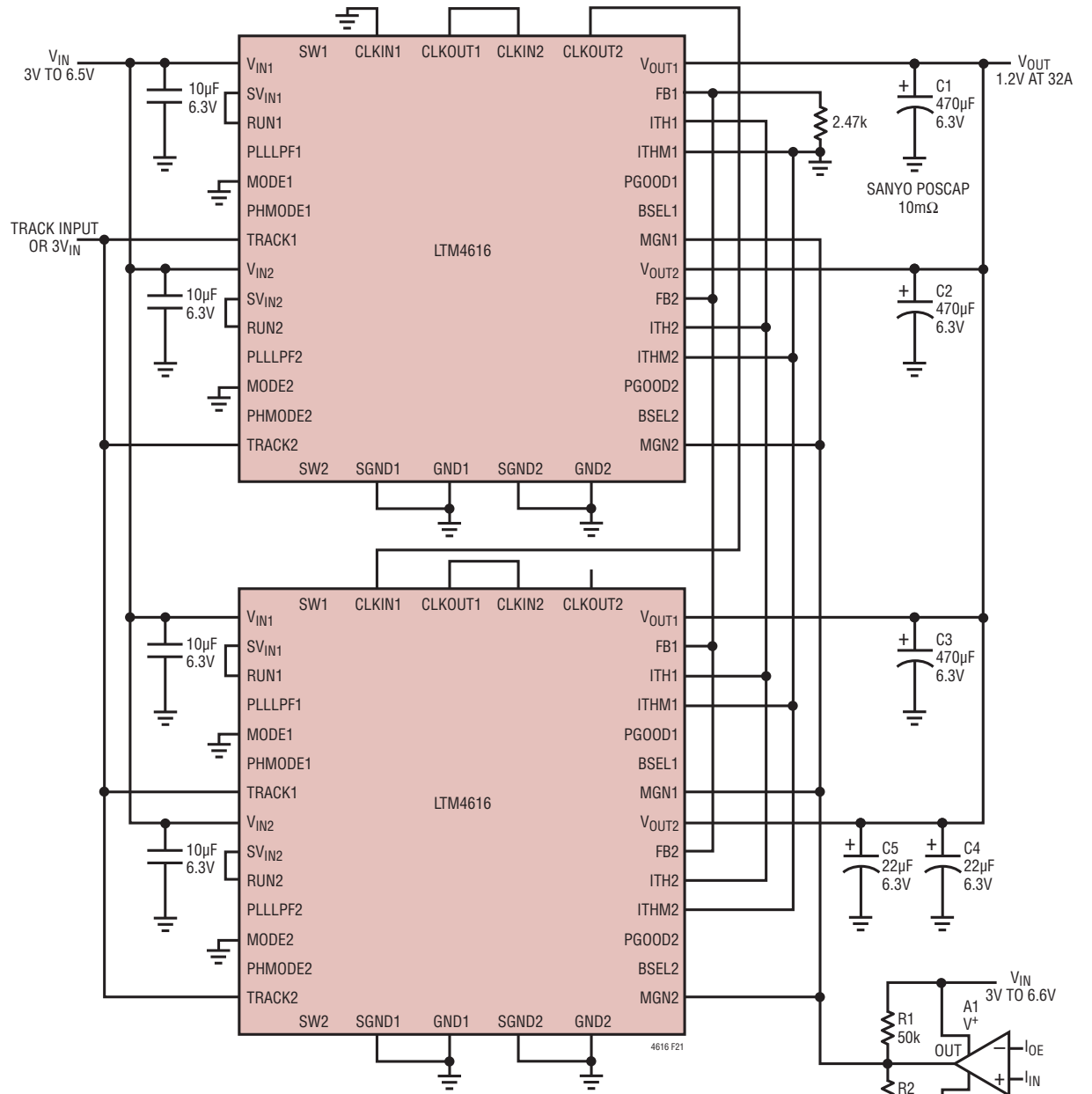


Figure 20. LTM4616 Output Sequencing Application

APPLICATIONS INFORMATION



BSEL: HIGH = 10%
 FLOAT = 15%
 LOW = 5%

A1, A2 PERICOM P174ST1G126CEX
 TOSHIBA TC75Z126AFE

OE	IN	OUT	MGN	MARGIN VALUE
H	H	H	H	+ Value of BSEL Selection
H	L	L	L	- Value of BSEL Selection
L	X	Z	V _{IN} /2	No Margin

OPTIONAL MARGINING CIRCUIT,
 IF NOT USED TIE THE MGN PINS TO V_{OUT}

Figure 21. Four Phase in Parallel, 1.2V at 32A

APPLICATIONS INFORMATION

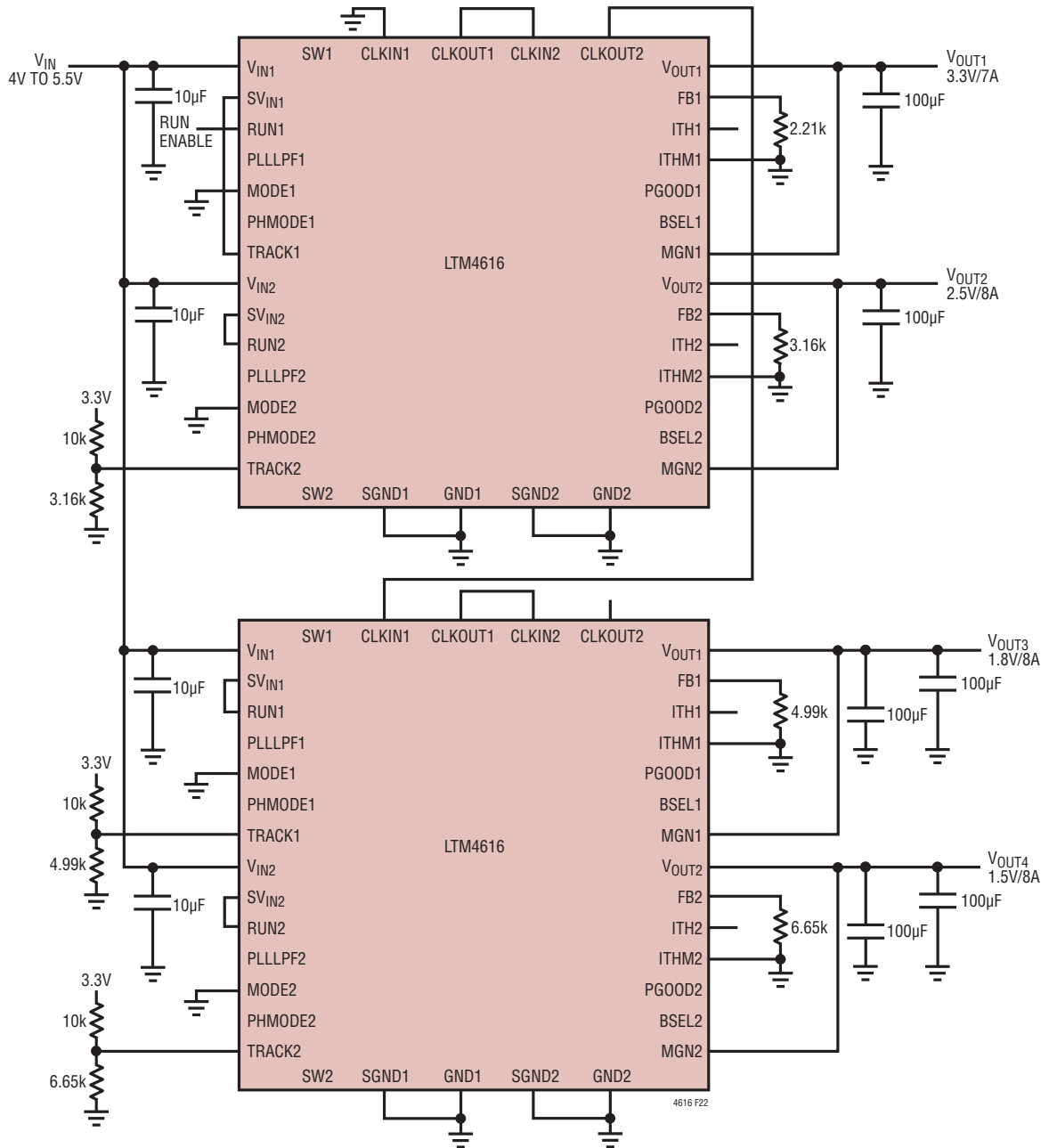
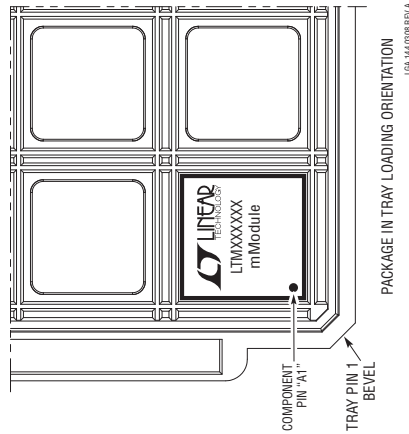
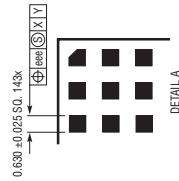
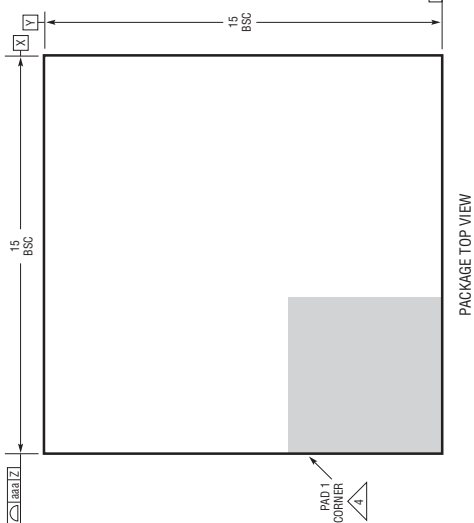
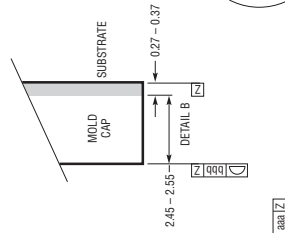
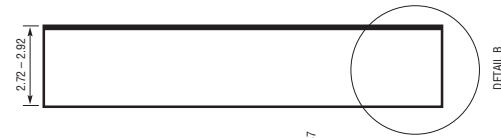
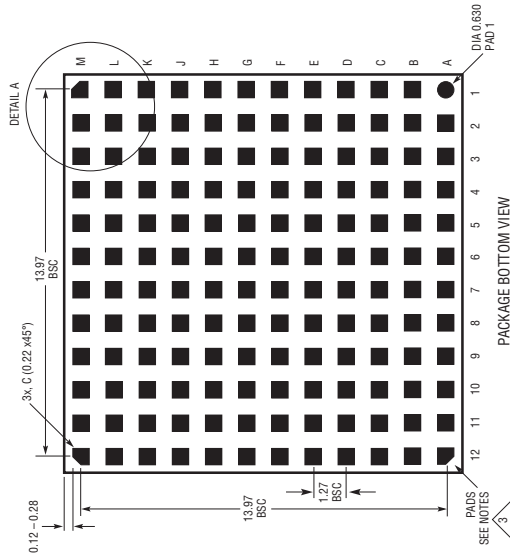


Figure 22. 4-Phase, Four Outputs (3.3V, 2.5V, 1.8V and 1.5V) with Tracking

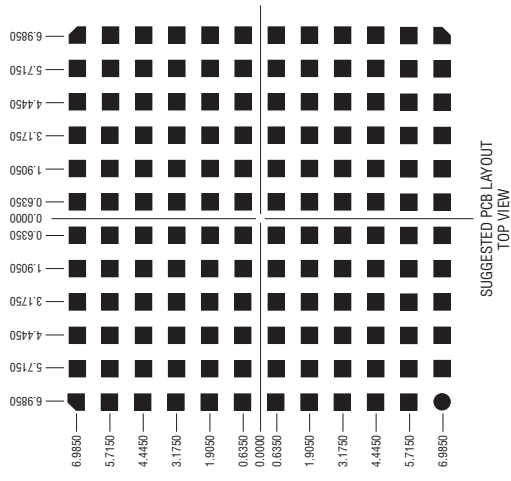
PACKAGE DESCRIPTION

LGA Package
144-Lead (15mm × 15mm × 2.82mm)
 (Reference LTC DWG # 05-08-1816 Rev A)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. LAND DESIGNATION PER JEDEC MO-222, SPP-010
 4. DETAILS OF PAD #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PAD #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM - Z - IS SEATING PLANE
 6. THE TOTAL NUMBER OF PADS: 144

SYMBOL	TOLERANCE
aaa	0.10
bbb	0.10
eee	0.05



PACKAGE DESCRIPTION

Pin Assignment Table
(Arranged by Pin Number)

PIN NAME	PIN NAME	PIN NAME	PIN NAME	PIN NAME	PIN NAME
A1	GND1	B1	GND1	C1	V _{IN1}
A2	GND1	B2	GND1	D1	V _{IN1}
A3	GND1	B3	GND1	E1	V _{IN1}
A4	GND1	B4	GND1	F1	V _{IN1}
A5	GND1	B5	GND1	D2	V _{IN1}
A6	BSEL1	B6	SW1	E2	V _{IN1}
A7	CLKIN1	C2	V _{IN1}	F2	V _{IN1}
A8	MODE1	C3	GND1	E3	V _{IN1}
A9	PHMODE1	C4	GND1	F3	V _{IN1}
A10	MGN1	C5	GND1	E4	V _{IN1}
A11	PGOOD1	C6	GND1	F4	V _{IN1}
A12	GND1	C7	GND1	E5	SV _{IN1}
		D6	GND1	F5	SGND1
		D7	GND1	E6	PLLFLTR1
		D8	FB1	F6	RUN1
		D9	V _{OUT1}	E7	ITHM1
		D10	V _{OUT1}	F7	CLKOUT1
		D11	V _{OUT1}	E8	TRACK1
		D12	V _{OUT1}	F8	ITH1
				E9	V _{OUT1}
				F9	V _{OUT1}
				E10	V _{OUT1}
				F10	V _{OUT1}
				E11	V _{OUT1}
				F11	V _{OUT1}
				E12	V _{OUT1}
				F12	V _{OUT1}

PIN NAME	PIN NAME	PIN NAME	PIN NAME	PIN NAME	PIN NAME
G1	GND2	H1	GND2	J1	V _{IN2}
G2	GND2	H2	GND2	K1	V _{IN2}
G3	GND2	H3	GND2	L1	V _{IN2}
G4	GND2	H4	GND2	M1	V _{IN2}
G5	GND2	H5	GND2	J2	V _{IN2}
G6	BSEL2	H6	SW2	K2	V _{IN2}
G7	CLKIN2	J3	GND2	L2	V _{IN2}
G8	MODE2	J4	GND2	M2	V _{IN2}
G9	PHMODE2	J5	GND2	K3	GND2
G10	MGN2	J6	GND2	L3	V _{IN2}
G11	PGOOD2	J7	GND2	M3	V _{IN2}
G12	GND2	J8	GND2	L4	V _{IN2}
		J9	GND2	M4	V _{IN2}
		J10	GND2	K5	GND2
		J11	GND2	L5	SV _{IN2}
		J12	GND2	M5	SGND2
				L6	PLLFLTR2
				M6	RUN2
				L7	ITHM2
				M7	CLKOUT2
				L8	TRACK2
				M8	ITH2
				L9	V _{OUT2}
				M9	V _{OUT2}
				L10	V _{OUT2}
				M10	V _{OUT2}
				L11	V _{OUT2}
				M11	V _{OUT2}
				L12	V _{OUT2}
				M12	V _{OUT2}

RELATED PARTS

PART NUMBER	DESCRIPTION	COMMENTS
LTC2900	Quad Supply Monitor with Adjustable Reset Timer	Monitors Four Supplies; Adjustable Reset Timer
LTM4600	10A DC/DC μ Module	Basic 10A DC/DC μ Module, LGA Package
LTM4600HVMP	Military Plastic 10A DC/DC μ Module	Guaranteed Operation from -55°C to 125°C Ambient, LGA Package
LTM4601/ LTM4601A	12A DC/DC μ Module with PLL, Output Tracking/ Margining and Remote Sensing	Synchronizable, PolyPhase Operation, LTM4601-1/LTM4601A-1 Version has no Remote Sensing, LGA Package
LTM4602	6A DC/DC μ Module	Pin Compatible with the LTM4600, LGA Package
LTM4603	6A DC/DC μ Module with PLL and Output Tracking/ Margining and Remote Sensing	Synchronizable, PolyPhase Operation, LTM4603-1 Version has no Remote Sensing, Pin Compatible with the LTM4601, LGA Package
LTM4604	Low V _{IN} 4A DC/DC μ Module	$2.375\text{V} \leq V_{\text{IN}} \leq 5.5\text{V}$, $0.8\text{V} \leq V_{\text{OUT}} \leq 5\text{V}$, $9\text{mm} \times 15\text{mm} \times 2.3\text{mm}$ LGA Package
LTM4608	Low V _{IN} 8A DC/DC μ Module	$2.375\text{V} \leq V_{\text{IN}} \leq 5.5\text{V}$; $0.6\text{V} \leq V_{\text{OUT}} \leq 5\text{V}$; $9\text{mm} \times 15\text{mm} \times 2.8\text{mm}$ LGA Package
LTM8022/LTM8023	36V _{IN} , 1A and 2A DC/DC μ Module	Pin Compatible; $4.5\text{V} \leq V_{\text{IN}} \leq 36\text{V}$; $9\text{mm} \times 11.25\text{mm} \times 2.8\text{mm}$ LGA Package